

## High Noise Immunity 42 V Input Voltage 70 mA Voltage Tracker for Industrial Applications

NO.EY-513-190411

### OVERVIEW

The R1540x is a voltage tracker featuring input voltage in the range of 3.5 V to 42 V. Highly accurate output voltage which attributes to CE/ADJ pin achieves successful sequence control of the integrated off-board sensor module. Strong enough not to require the circuit to avoid external electromagnetic interference (EMI) and this contributes space saving. This is a high-reliability semiconductor device for industrial applications (-Y) that has passed both the screening at high temperature and the reliability test with extended hours.

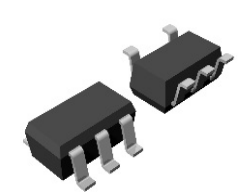
### KEY BENEFITS

- Excellent noise immunity provides effective shielding against EMI.
- Lower stand-by current consumption leads to energy saving of the whole system to prolong battery life.
- Response to requirements for sequence control in the system with integrated sensors.

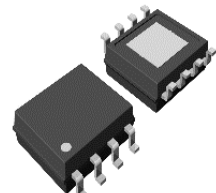
### KEY SPECIFICATIONS

- Input Voltage Range (Maximum Rating):  
3.5 V to 42.0 V (50.0 V)
- Supply Current: Typ. 60  $\mu$ A
- Standby Current: Typ. 0.1  $\mu$ A
- Tracking Voltage Range: 2.2 V to 14 V
- Tracking Voltage Accuracy:  $\pm 15$  mV  
( $-40^{\circ}\text{C} \leq T_a \leq 125^{\circ}\text{C}$ ,  $V_{\text{CE/ADJ}} = 5$  V)
- Output Current 70 mA
- Ripple Rejection: Typ. 80 dB (f = 100 Hz)
- Protections: Thermal Shutdown, Output Current Limiting and Short-circuit Current Limiting

### PACKAGE

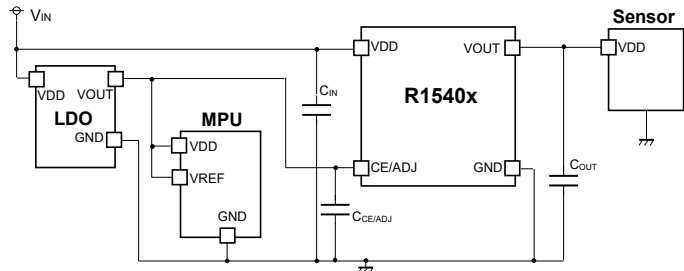


**SOT-23-5**  
2.9 x 2.8 x 1.1 (mm)



**HSOP-8E**  
5.2 x 6.2 x 1.45 (mm)

### TYPICAL APPLICATION



$C_{\text{IN}}$ : 0.1 $\mu$ F,  $C_{\text{OUT}}$ : 10 $\mu$ F,  $C_{\text{CE/ADJ}}$ : 0.1 $\mu$ F, Ceramic capacitor

### SELECTION GUIDE

| Product Name     | Package  | Quantity per Reel |
|------------------|----------|-------------------|
| R1540N001B-TR-YE | SOT-23-5 | 3,000 pcs         |
| R1540S001B-E2-YE | HSOP-8E  | 1,000 pcs         |

### APPLICATIONS

- Off-board sensors and power supply systems for analog to digital converters (ADC)

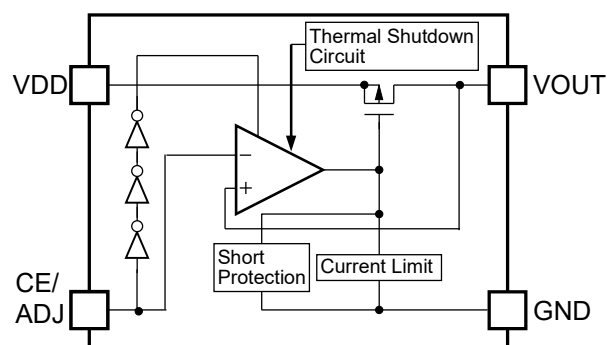
## SELECTION GUIDE

R1540x offers selectable packages corresponding to user's purpose.

### Selection Guide

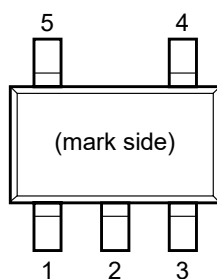
| Product Name     | Package  | Quantity per Reel | Pb Free | Halogen Free |
|------------------|----------|-------------------|---------|--------------|
| R1540N001B-TR-YE | SOT-23-5 | 3,000 pcs         | Yes     | Yes          |
| R1540S001B-E2-YE | HSOP-8E  | 1,000 pcs         | Yes     | Yes          |

## BLOCK DIAGRAM

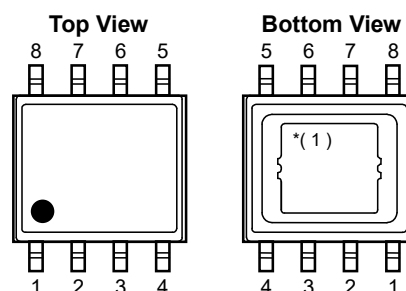


**R1540x001B Block Diagram**

## PIN DESCRIPTIONS



R1540N (SOT-23-5) Pin Configuration



R1540S (HSOP-8E) Pin Configuration

### R1540N Pin Descriptions

| Pin No. | Symbol             | Description                                    |
|---------|--------------------|--|
| 1       | CE/ADJ             | Chip Enable and Adjustment Pin (Active - High) |
| 2       | GND <sup>(2)</sup> | Ground Pin                                     |
| 3       | VDD                | Input Pin                                      |
| 4       | VOUT               | Output Pin                                     |
| 5       | GND <sup>(2)</sup> | Ground Pin                                     |

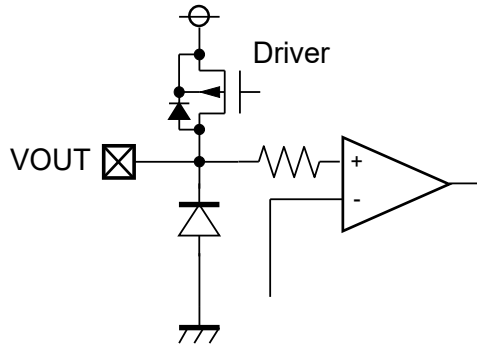
### R1540S Pin Descriptions

| Pin No. | Symbol             | Description                                    |
|---------|--------------------|--|
| 1       | VDD                | Input Pin                                      |
| 2       | VDD                | Input Pin                                      |
| 3       | NC                 | No Contact                                     |
| 4       | CE/ADJ             | Chip Enable and Adjustment Pin (Active - High) |
| 5       | GND <sup>(2)</sup> | Ground Pin                                     |
| 6       | GND <sup>(2)</sup> | Ground Pin                                     |
| 7       | NC                 | No Contact                                     |
| 8       | VOUT               | Output Pin                                     |

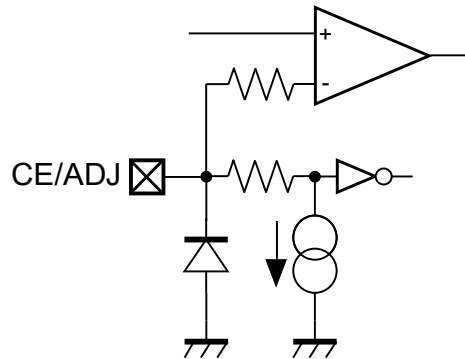
<sup>(1)</sup> The tab on the bottom of the package is substrate potential (GND). It is recommended that this tab to be connected to the ground plane on the board.

<sup>(2)</sup> The GND pins must be wired together on the board.

**INTERNAL EQUIVALENT CIRCUIT FOR EACH PIN**



**VOUT Pin Internal Equivalent Circuit Diagrams**



**CE/ADJ Pin Internal Equivalent Circuit Diagrams**

**ABSOLUTE MAXIMUM RATINGS**

| Symbol              | Parameter   |          | Rating                             | Unit |
|---------------------|---|----------|------------------------------------|------|
| V <sub>IN</sub>     | Input Voltage                                     |          | -0.3 to 50                         | V    |
|                     | Peak Voltage <sup>(1)</sup>                       |          | 60                                 | V    |
| V <sub>CE/ADJ</sub> | CE/ADJ Pin Input Voltage                          |          | -0.3 to 50                         | V    |
| V <sub>OUT</sub>    | V <sub>OUT</sub> Pin Output Voltage               |          | -0.3 to V <sub>IN</sub> + 0.3 ≤ 50 | V    |
| I <sub>OUT</sub>    | Output Current                                    |          | 95                                 | mA   |
| P <sub>D</sub>      | Power Dissipation <sup>(2)</sup><br>JEDEC STD. 51 | SOT-23-5 | 830                                | mW   |
|                     |   | HSOP-8E  | 3600                               |      |
| T <sub>j</sub>      | Junction Temperature Range                        |          | -40 to 150                         | °C   |
| T <sub>stg</sub>    | Storage Temperature Range                         |          | -55 to 150                         | °C   |

**ABSOLUTE MAXIMUM RATINGS**

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings are not assured.

**RECOMMENDED OPERATING CONDITIONS**

| Symbol              | Parameter                   | Rating     | Unit |
|---------------------|-----------------------------|------------|------|
| V <sub>IN</sub>     | Input Voltage               | 3.5 to 42  | V    |
| V <sub>CE/ADJ</sub> | CE/ADJ Input Pin Voltage    | 0 to 14    | V    |
| T <sub>a</sub>      | Operating Temperature Range | -40 to 125 | °C   |

**RECOMMENDED OPERATING CONDITONS**

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such ratings by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

<sup>(1)</sup> Duration time: 200 ms.

<sup>(2)</sup> Refer to POWER DISSIPATION for detailed information

## ELECTRICAL CHARACTERISTICS

$C_{IN} = 0.1 \mu\text{F}$ ,  $C_{OUT} = 10 \mu\text{F}$ ,  $V_{CE/ADJ} = 5.0 \text{ V}$  and  $V_{IN} = 14.0 \text{ V}$ , unless otherwise noted.

The specifications surrounded by   are guaranteed by design engineering at  $-40^\circ\text{C} \leq T_a \leq 125^\circ\text{C}$ .

### R1540x001B Electrical Characteristics

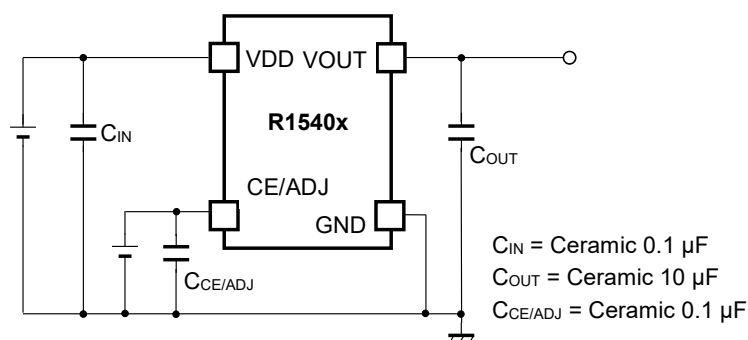
( $T_a = 25^\circ\text{C}$ )

| Symbol                               | Parameter  | Conditions  | Min.  | Typ.  | Max.  | Unit   |
|--------------------------------------|--|---|---|---|---|--|
| $I_{SS}$                             | Supply Current                                   | $V_{IN} = 14 \text{ V}$ , $I_{OUT} = 0 \text{ mA}$  |   | 60  | <span style="border: 1px solid black; padding: 0 2px;">100</span> | $\mu\text{A}$  |
| $I_{standby}$                        | Standby Current                                  | $V_{IN} = 42 \text{ V}$ , $V_{CE/ADJ} = 0 \text{ V}$  |   | 0.1   | <span style="border: 1px solid black; padding: 0 2px;">1.0</span> | $\mu\text{A}$  |
| $\Delta V_O$                         | Tracking Voltage Accuracy                        | $8 \text{ V} \leq V_{IN} \leq 24 \text{ V}$<br>$1 \text{ mA} \leq I_{OUT} \leq 70 \text{ mA}$             | $V_{CE/ADJ} = 5.0 \text{ V}$                                      |   | <span style="border: 1px solid black; padding: 0 2px;">15</span>  | mV   |
|                                      |  | $6 \text{ V} \leq V_{IN} \leq 42 \text{ V}$<br>$1 \text{ mA} \leq I_{OUT} \leq 10 \text{ mA}$             |   |   |   |  |
|                                      |  | $V_{IN} = 15 \text{ V}$<br>$I_{OUT} = 1 \text{ mA}$   | $2.2 \text{ V} \leq V_{CE/ADJ} \leq 5.0 \text{ V}$                | <span style="border: 1px solid black; padding: 0 2px;">-15</span> |   | <span style="border: 1px solid black; padding: 0 2px;">15</span> |
|                                      | $5.0 \text{ V} < V_{CE/ADJ} \leq 14.0 \text{ V}$ | <span style="border: 1px solid black; padding: 0 2px;">-18</span>   |   | <span style="border: 1px solid black; padding: 0 2px;">18</span>  |   |  |
| $\Delta V_{OUT} / \Delta I_{OUT}$    | Load Regulation                                  | $V_{IN} = 8 \text{ V}$ , $1 \text{ mA} \leq I_{OUT} \leq 70 \text{ mA}$                                   | <span style="border: 1px solid black; padding: 0 2px;">-2</span>  |   | <span style="border: 1px solid black; padding: 0 2px;">2</span>   | mV   |
| $\Delta V_{OUT} / \Delta V_{IN}$     | Line Regulation                                  | $6 \text{ V} \leq V_{IN} \leq 42 \text{ V}$ , $I_{OUT} = 1 \text{ mA}$                                    | <span style="border: 1px solid black; padding: 0 2px;">-8</span>  |   | <span style="border: 1px solid black; padding: 0 2px;">8</span>   | mV   |
| $\Delta V_{OUT} / \Delta V_{CE/ADJ}$ | CE/ADJ Regulation                                | $2.2 \text{ V} \leq V_{CE/ADJ} \leq 14 \text{ V}$ , $I_{OUT} = 1 \text{ mA}$ ,<br>$V_{IN} = 15 \text{ V}$ | <span style="border: 1px solid black; padding: 0 2px;">-1</span>  |   | <span style="border: 1px solid black; padding: 0 2px;">1</span>   | mV/V   |
| $V_{DIF}$                            | Dropout Voltage                                  | $I_{OUT} = 70 \text{ mA}$   |   | 1.3   | <span style="border: 1px solid black; padding: 0 2px;">2.1</span> | V  |
| $I_{LIM}$                            | Output Current Limit                             | $V_{IN} = 8 \text{ V}$  | <span style="border: 1px solid black; padding: 0 2px;">80</span>  | 120   |   | mA   |
| $I_{SC}$                             | Short Current Limit                              | $V_{IN} = 8 \text{ V}$ , $V_{OUT} = 0 \text{ V}$  | <span style="border: 1px solid black; padding: 0 2px;">20</span>  | 40  |   | mA   |
| $V_{CE/ADJH}$                        | CE/ADJ Pin Input Voltage, high                   | $V_{IN} = 15 \text{ V}$   | <span style="border: 1px solid black; padding: 0 2px;">2.0</span> |   | <span style="border: 1px solid black; padding: 0 2px;">14</span>  | V  |
| $V_{CE/ADJL}$                        | CE/ADJ Pin Input Voltage, low                    | $V_{IN} = 42 \text{ V}$   | <span style="border: 1px solid black; padding: 0 2px;">0</span>   |   | <span style="border: 1px solid black; padding: 0 2px;">1.0</span> | V  |
| $I_{PD}$                             | CE/ADJ Pin Pull Down Current                     | $V_{IN} = 42 \text{ V}$ , $V_{CE/ADJ} = 2 \text{ V}$  |   | 0.2   | <span style="border: 1px solid black; padding: 0 2px;">1.0</span> | $\mu\text{A}$  |
| $T_{TSD}$                            | Thermal Shutdown Detection Temperature           | Junction Temperature  | 150   | 165   |   | $^\circ\text{C}$   |
| $T_{TSR}$                            | Thermal Shutdown Released Temperature            | Junction Temperature  | 128   | 135   |   | $^\circ\text{C}$   |

All test items listed under Electrical Characteristics are done under the pulse load condition ( $T_j \approx T_a = 25^\circ\text{C}$ ).

## TYPICAL APPLICATION

### TYPICAL APPLICATION



**R1540x Typical Application**

## TECHNICAL NOTES

### Phase Compensation

R1540x adopts capacitance and Equivalent Series Resistance (ESR) for phase compensation to ensure stable operation even with load varying current. For this end, the capacitor of 10  $\mu$ F or more is essential. A certain amount of ESR may cause unstable output voltage. Fully take temperature and frequency characteristics into consideration when evaluating the circuit. Place the capacitor of 0.1  $\mu$ F or more between VDD and GND with using short leads and short printed circuit traces.

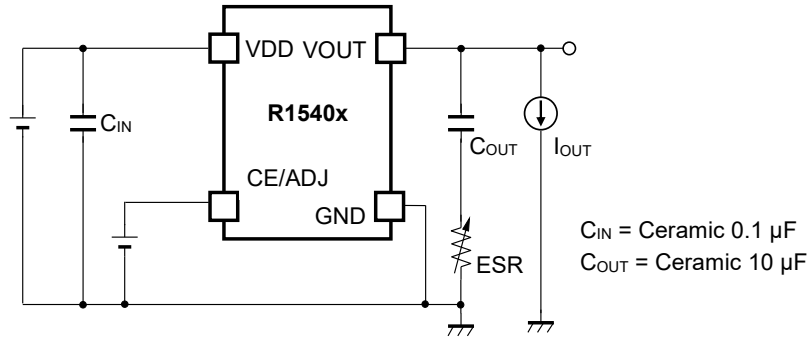
### PCB Layout

SOT-23-5 package: connect Nos. 2 and 5 of GND pin together.

HSOP-8E package: connect Nos. 5 and 6 of GND pin together.

**ESR vs. output current characteristics**

Using ceramic output capacitor is highly recommended although availability of another low-ESR capacitors. The mutual relations between the output current ( $I_{OUT}$ ) causes noise under the specified value and the ESR are indicated below for reference.



**Measurement Conditions**

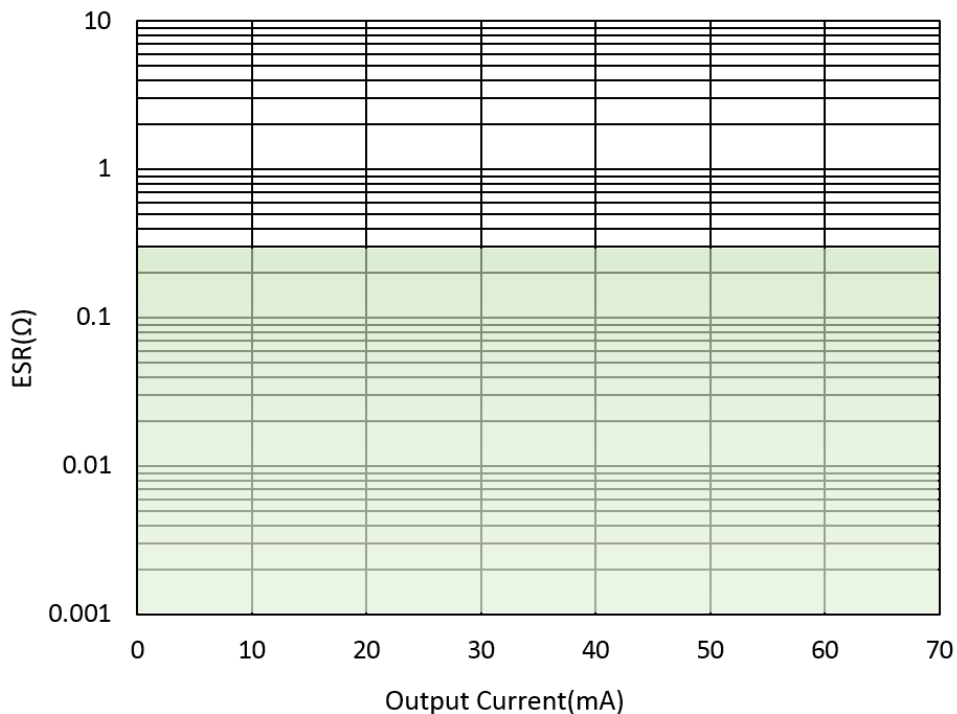
Frequency Band: 10 Hz to 2 MHz

Temperature: -40°C to 125°C

Shaded portion: Noise level is 40 μV (average) or below

Capacitors:  $C_{IN}$  = 0.1 μF of Ceramic,  $C_{OUT}$  = 10 μF of Ceramic

**R1540x001B**





## **THEORY OF OPERATION**

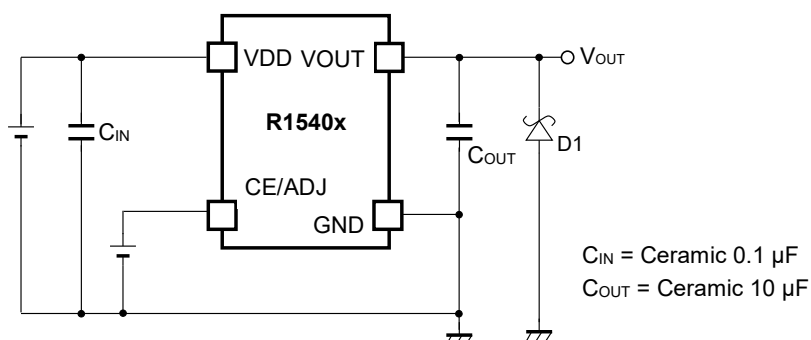
### **Thermal Shutdown**

Thermal Shutdown occurs when the device's junction temperature reaches 165°C (Typ.) at which point the regulator will automatically shut down. Then the regulator resumes from the stand-by state when the junction temperature decreases below 135°C (Typ.). Unless the cause of overheating is eliminated, the device cycles on and off to generate pulse output.

## APPLICATION INFORMATION

### Typical Application for IC Chip Breakdown Prevention

A sudden surge of current flowing through the VOUT pin during a short to GND leads to negative voltage due to resonance generated between the impedance of the wire and the output capacitor, C<sub>2</sub>. Consequently, large short-circuit current may destroy the IC or a load device in some types of pattern boards. It is highly recommended to connect schottky diode, D1, between VOUT pin and GND to prevent the IC from being destroyed.



**R1540x Typical Application for IC Chip Breakdown Prevention**

**Electromagnetic Noise Immunity**

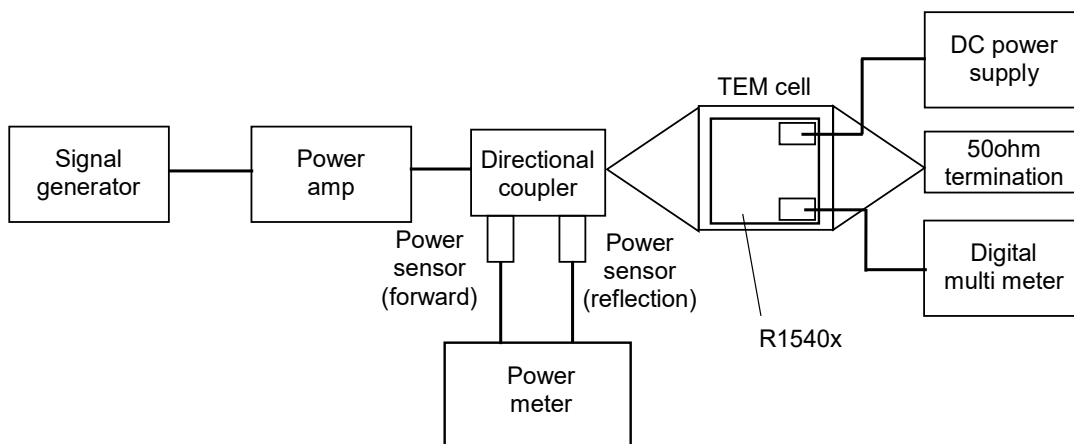
An output voltage may linearly varies in some regulators due to electromagnetic noise. R1540x adopts the techniques on its circuits to prevent this voltage variation. The noise immunity test indicated below was conducted to confirm that R1540x is fairly robust to electromagnetic noise over a broad frequency band.

DC power supply : apply  $V_{IN} = 14\text{ V}$ ,  $V_{CE/ADJ} = 5\text{ V}$

Digital multi meter : measure the output DC voltage of R1540

Signal generator : apply high frequency signal of 150 kHz to 1 GHz

Power meter : measure the intensity of signal so as to sense the surface electric field intensity of 800 V/m

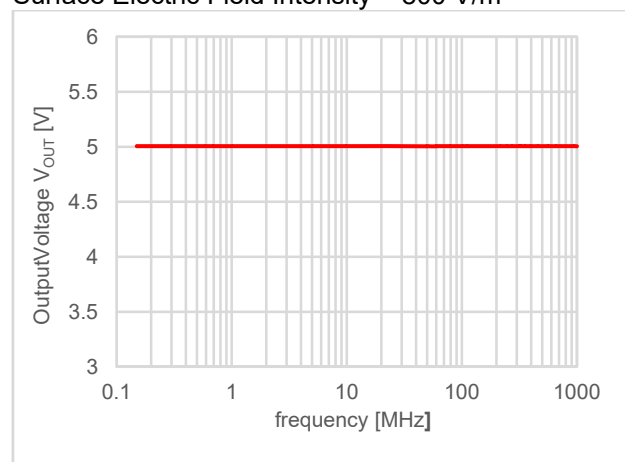


**Block Diagram for Immunity Test Based on IEC 62132-2 TEM cell**

EMS Characteristics (TEMcell Applied : 800 V/m)

$V_{IN} = 14\text{ V}$ ,  $V_{CE/ADJ} = 5\text{ V}$ ,

Surface Electric Field Intensity = 800 V/m

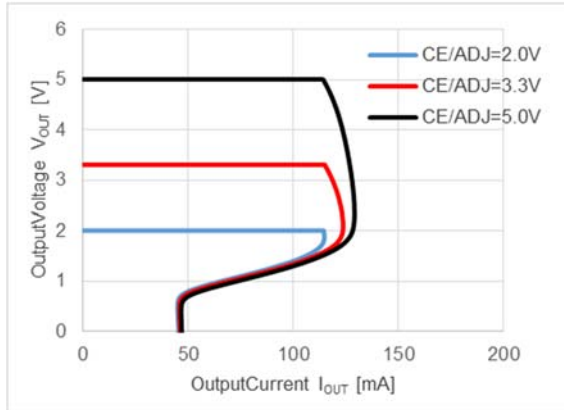


## TYPICAL CHARACTERISTICS

Typical Characteristics are intended to be used as reference data, they are not guaranteed

### 1) Output voltage vs Output Current

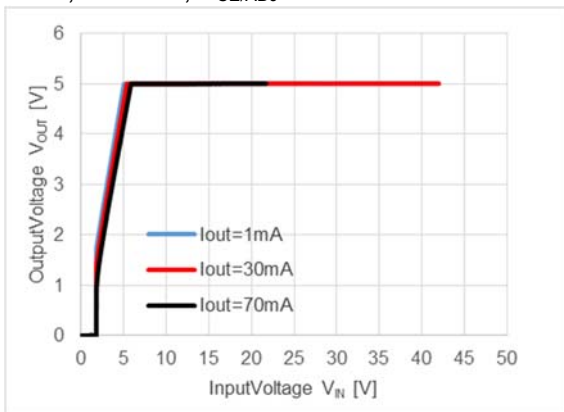
$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C



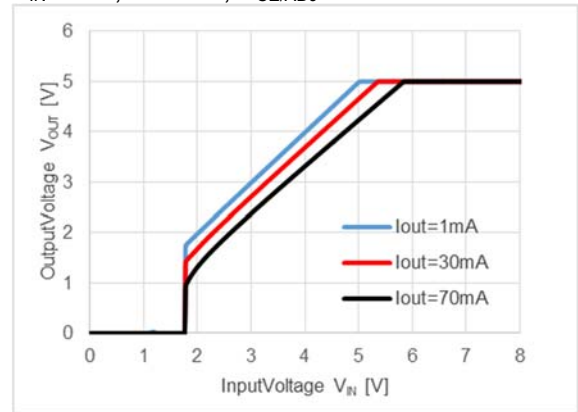
### 2) Output voltage vs Input Voltage

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$ =25°C

$V_{IN}$  = 0 V,  $\leq$  42 V,  $V_{CE/ADJ}$  = 5 V



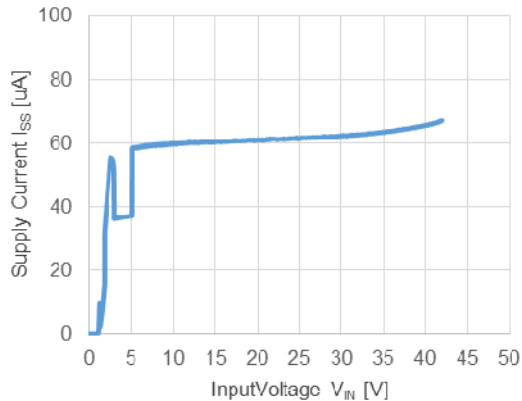
$V_{IN}$  = 0 V,  $\leq$  8 V,  $V_{CE/ADJ}$  = 5 V



### 3) Supply Current vs Input Voltage

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C

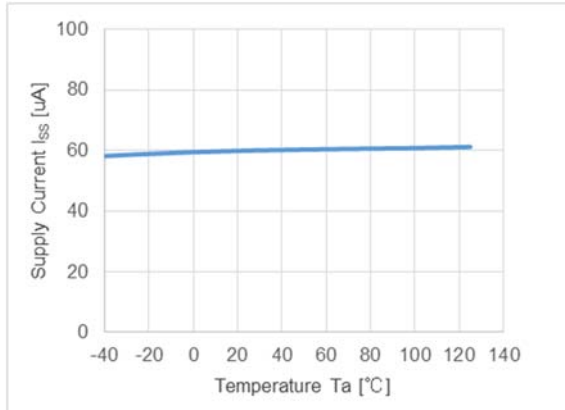
$V_{IN}$  = 0 V  $\leq$  42 V,  $V_{CE/ADJ}$  = 5 V,  $I_{OUT}$  = 0 mA



4) Supply Current vs Temperature

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F

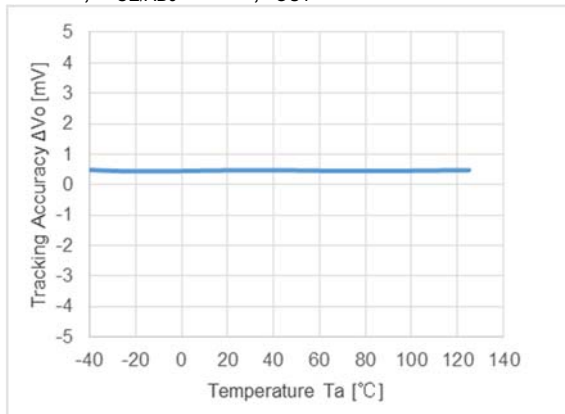
$V_{IN}$  = 14 V,  $V_{CE/ADJ}$  = 5 V,  $I_{OUT}$  = 0 mA



5) Tracking Accuracy vs Temperature

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F

$V_{IN}$  = 14 V,  $V_{CE/ADJ}$  = 5 V,  $I_{OUT}$  = 1 mA

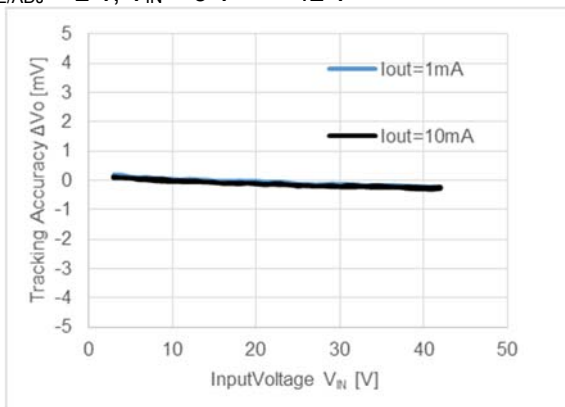


6) Tracking Accuracy vs Input Voltage

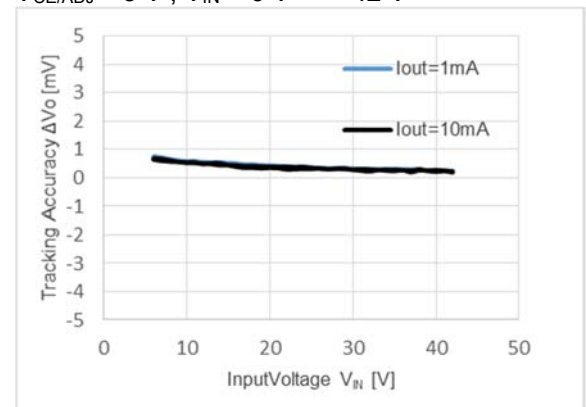
$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,

$T_a = 25^\circ\text{C}$

$V_{CE/ADJ} = 2$  V,  $V_{IN} = 3$  V  $\Leftrightarrow$  42 V



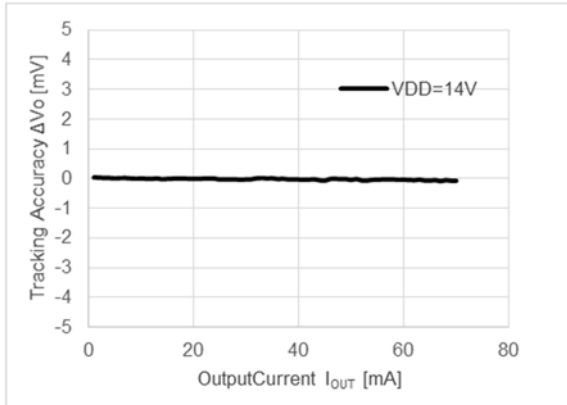
$V_{CE/ADJ} = 5$  V,  $V_{IN} = 6$  V  $\Leftrightarrow$  42 V



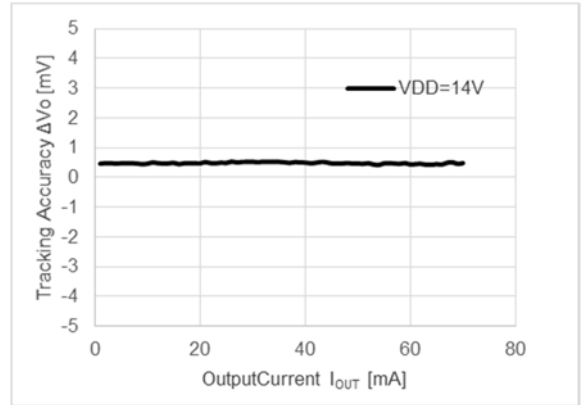
7) Tracking Accuracy vs Load Current

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C

$V_{CE/ADJ}$  = 2 V,  $I_{OUT}$  = 1mA  $\Leftrightarrow$  70 mA



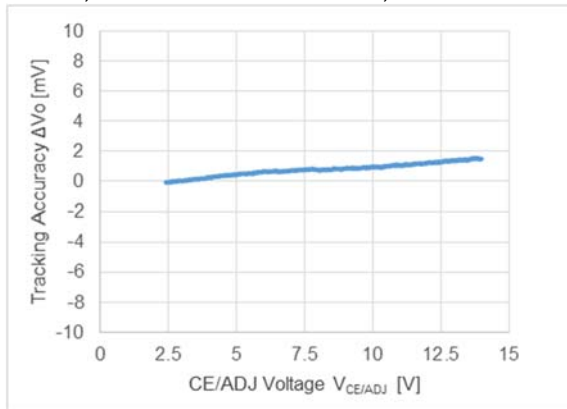
$V_{CE/ADJ}$  = 5 V,  $I_{OUT}$  = 1mA  $\Leftrightarrow$  70 mA



8) Tracking Accuracy vs CE/ADJ Voltage

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C

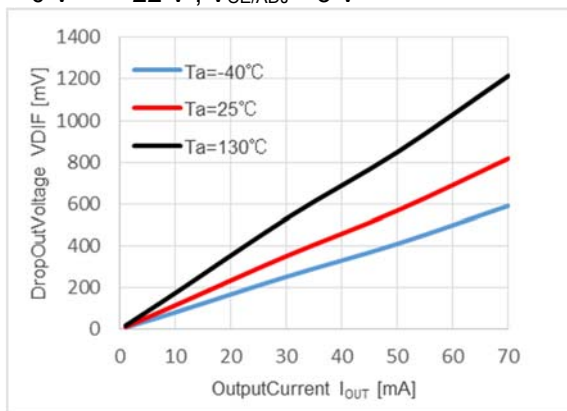
$V_{IN}$  = 15 V,  $V_{CE/ADJ}$  = 2.4 V  $\Leftrightarrow$  14 V,  $I_{OUT}$  = 1 mA



9) Dropout Voltage vs Output Current

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$ =25°C

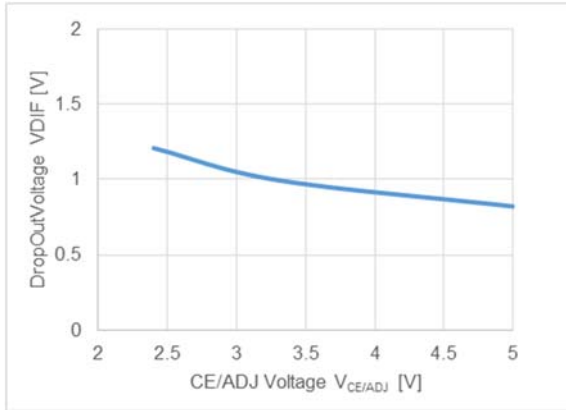
$V_{IN}$  = 0 V  $\Leftrightarrow$  22 V,  $V_{CE/ADJ}$  = 5 V



10) Dropout Voltage vs CE/ADJ Voltage

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a=25^\circ\text{C}$

$V_{IN} = 0\text{ V} \Leftrightarrow 22\text{ V}$ ,  $I_{OUT}=70\text{ mA}$

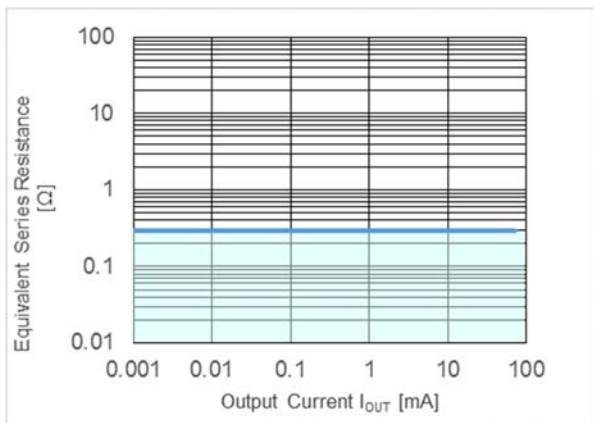


11) Equivalent Series Resistance vs Output Current

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10 $\mu$ F,  $T_a=25^\circ\text{C}$

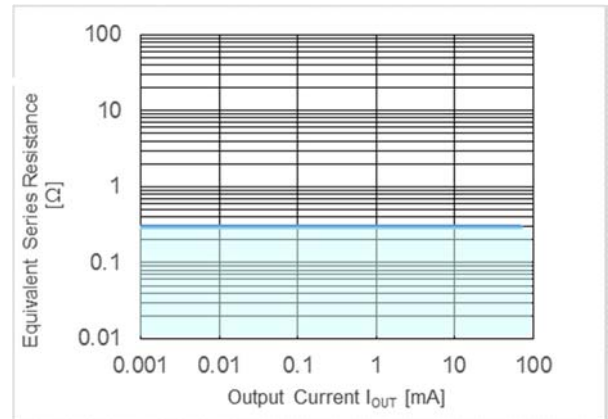
$V_{IN} = 4\text{ V} \Leftrightarrow 42\text{ V}$ ,  $V_{CE/ADJ} = 2\text{ V}$

$T_a = -40^\circ\text{C} / 25^\circ\text{C} / 130^\circ\text{C}$



$V_{IN} = 7\text{ V} \Leftrightarrow 42\text{ V}$ ,  $V_{CE/ADJ} = 5\text{ V}$

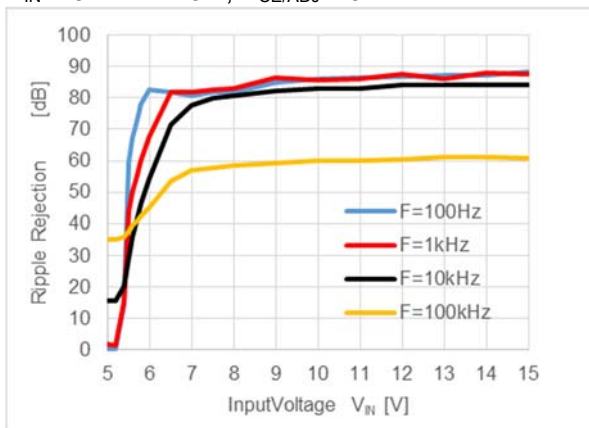
$T_a = -40^\circ\text{C} / 25^\circ\text{C} / 130^\circ\text{C}$



12) Ripple Rejection vs Input Voltage

$C_{IN}$  = none,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a = 25^\circ\text{C}$

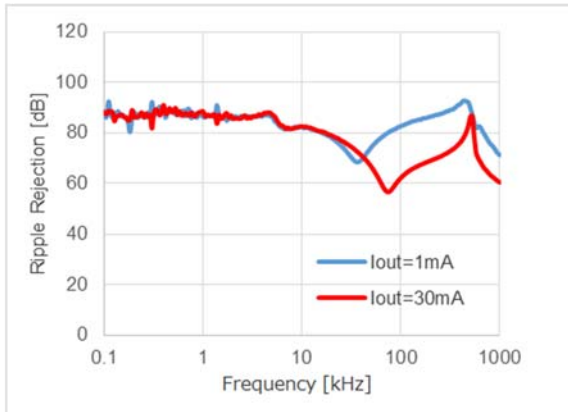
$V_{IN} = 5\text{ V} \Leftrightarrow 15\text{ V}$ ,  $V_{CE/ADJ} = 5\text{ V}$



## 13) Ripple Rejection vs Frequency

$C_{IN}$  = none,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C

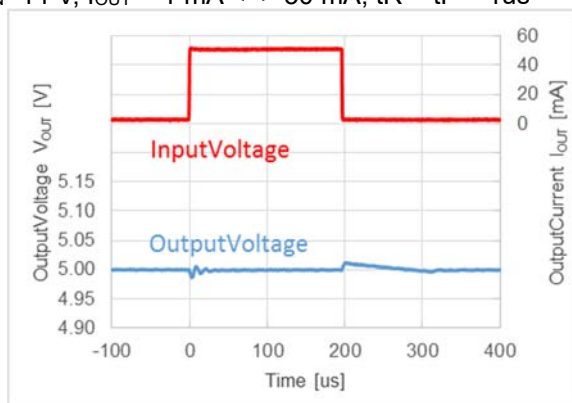
$V_{IN}$  = 14 V,  $V_{CE/ADJ}$  = 2 V



## 14) Load Transient Response

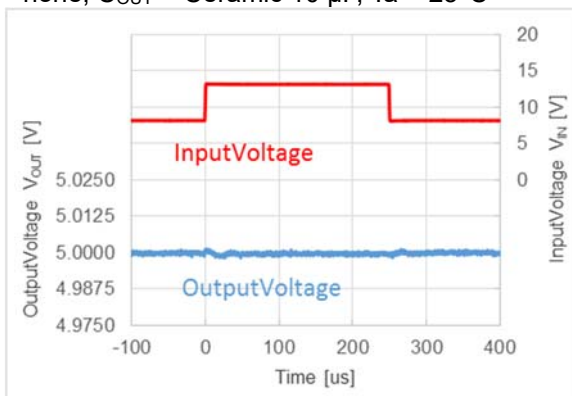
$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C

$V_{IN}$  = 14 V,  $I_{OUT}$  = 1 mA  $\Leftrightarrow$  50 mA,  $t_R$  =  $t_F$  = 1  $\mu$ s



## 15) Input Transient Response

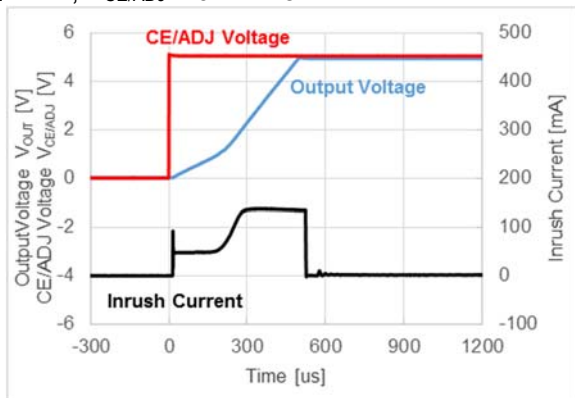
$C_{IN}$  = none,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C





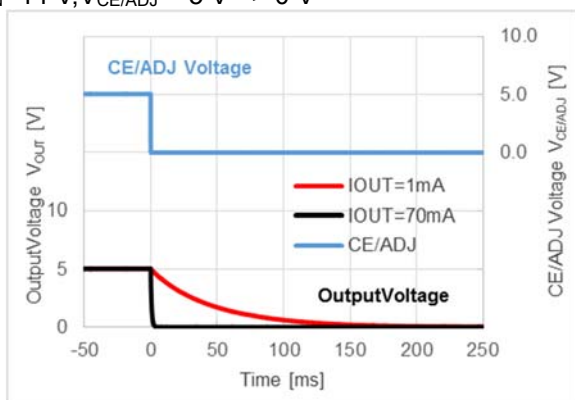
16) Turn-on Speed with CE/ADJ pin

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C  
 $V_{IN}$ =14 V,  $V_{CE/ADJ}$  = 0 V => 5 V



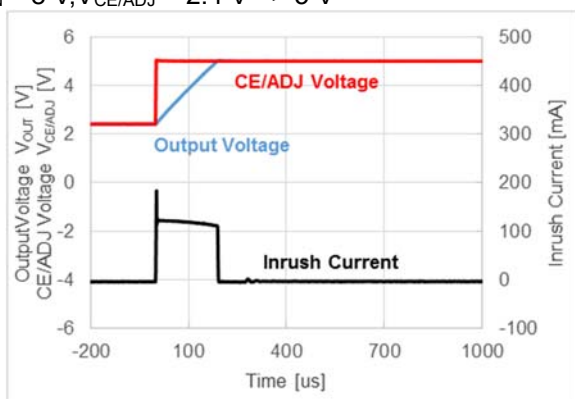
17) Turn-off Speed with CE/ADJ pin

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10 $\mu$ F,  $T_a$  = 25°C  
 $V_{IN}$ =14 V,  $V_{CE/ADJ}$  = 5 V => 0 V

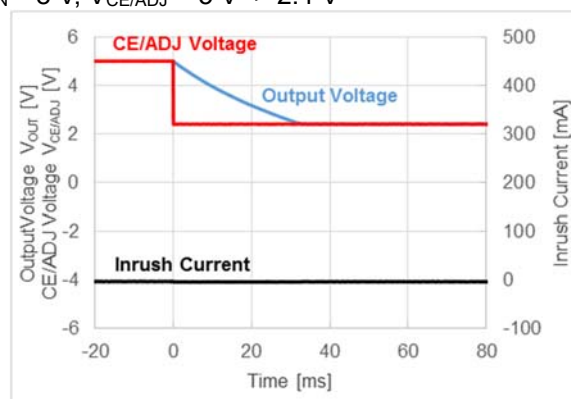


18) CE/ADJ Excess/Inrush Current

$C_{IN}$  = none,  $C_{OUT}$  = Ceramic 10 $\mu$ F,  $T_a$  = 25°C  
 $V_{IN}$  = 8 V,  $V_{CE/ADJ}$  = 2.4 V => 5 V



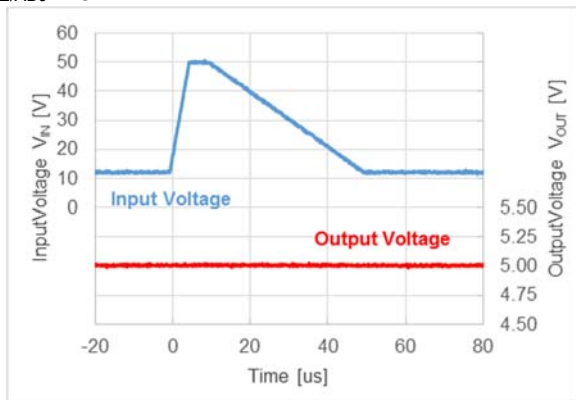
$V_{IN}$  = 8 V,  $V_{CE/ADJ}$  = 5 V => 2.4 V



19) Load Dump

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C

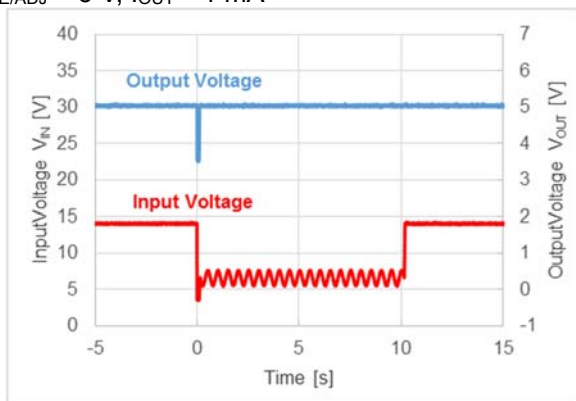
$V_{CE/ADJ}$  = 5 V



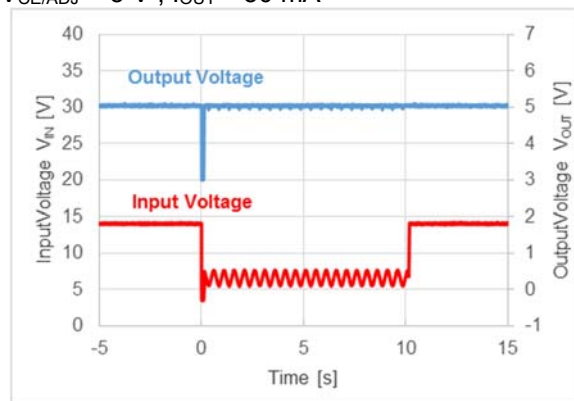
20) Cranking

$C_{IN}$  = Ceramic 0.1  $\mu$ F,  $C_{OUT}$  = Ceramic 10  $\mu$ F,  $T_a$  = 25°C

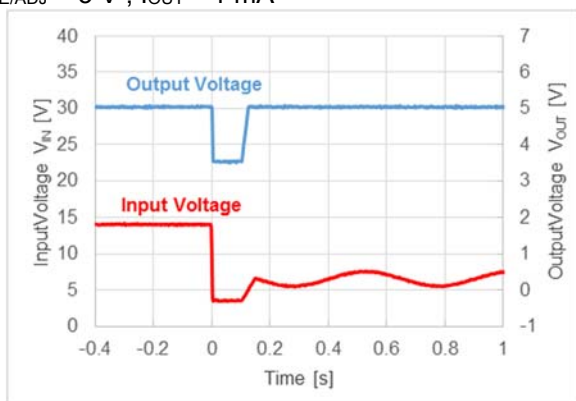
$V_{CE/ADJ}$  = 5 V,  $I_{OUT}$  = 1 mA



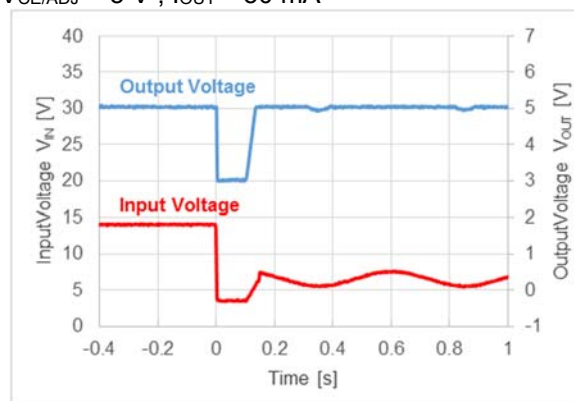
$V_{CE/ADJ}$  = 5 V,  $I_{OUT}$  = 50 mA



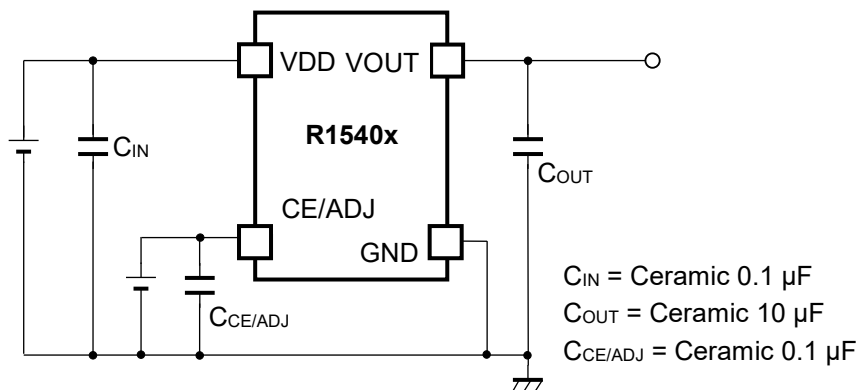
$V_{CE/ADJ}$  = 5 V,  $I_{OUT}$  = 1 mA



$V_{CE/ADJ}$  = 5 V,  $I_{OUT}$  = 50 mA



**Test Circuit**



**R1540x circuit for measuring Typical Characteristics**

**Measurement Components of Typical Characteristics**

| Symbol    | Capacitance | Measurement item | Manufacturer | Parts number         |
|-----------|-------------|------------------|--------------|----------------------|
| $C_{IN}$  | 0.1 $\mu$ F | All              | TDK          | CGA4J2X7R2A104K125AA |
| $C_{OUT}$ | 10 $\mu$ F  | All              | TDK          | CGA6P1X7R1E106K      |

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

**Measurement Conditions**

| Item             | Measurement Conditions   |
|------------------|--|
| Environment      | Mounting on Board (Wind Velocity = 0 m/s)  |
| Board Material   | Glass Cloth Epoxy Plastic (Four-Layer Board)   |
| Board Dimensions | 76.2 mm × 114.3 mm × 0.8 mm  |
| Copper Ratio     | Outer Layer (First Layer): Less than 95% of 50 mm Square<br>Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square<br>Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square |
| Through-holes    | φ 0.3 mm × 7 pcs   |

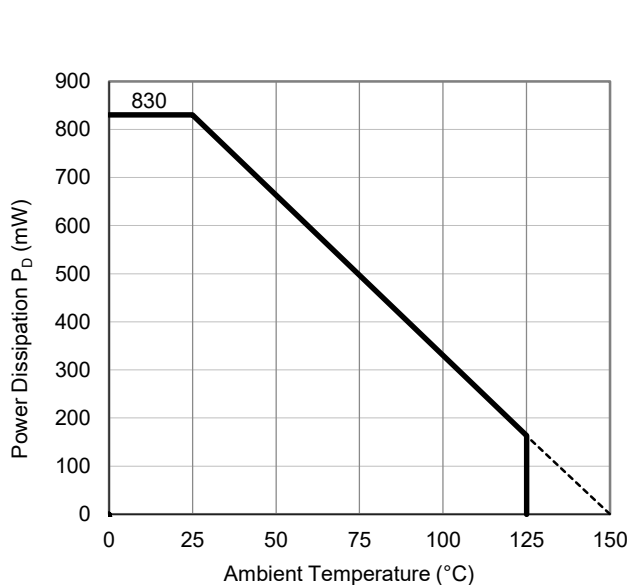
**Measurement Result**

(Ta = 25°C, Tjmax = 150°C)

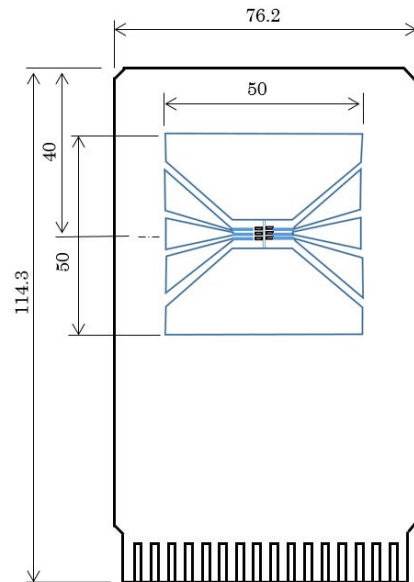
| Item                                     | Measurement Result |
|--|--------------------|
| Power Dissipation                        | 830 mW             |
| Thermal Resistance (θja)                 | θja = 150°C/W      |
| Thermal Characterization Parameter (ψjt) | ψjt = 51°C/W       |

θja: Junction-to-Ambient Thermal Resistance

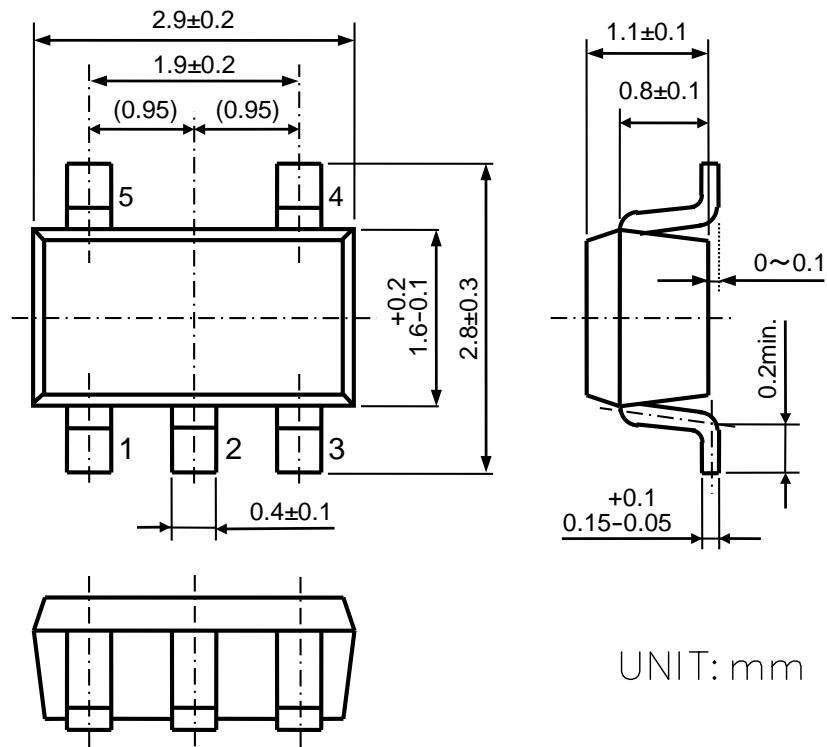
ψjt: Junction-to-Top Thermal Characterization Parameter



**Power Dissipation vs. Ambient Temperature**



**Measurement Board Pattern**



SOT-23-5 Package Dimensions

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

**Measurement Conditions**

| Item             | Measurement Conditions   |
|------------------|--|
| Environment      | Mounting on Board (Wind Velocity = 0 m/s)  |
| Board Material   | Glass Cloth Epoxy Plastic (Four-Layer Board)   |
| Board Dimensions | 76.2 mm × 114.3 mm × 0.8 mm  |
| Copper Ratio     | Outer Layer (First Layer): Less than 95% of 50 mm Square<br>Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square<br>Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square |
| Through-holes    | φ 0.3 mm × 21 pcs  |

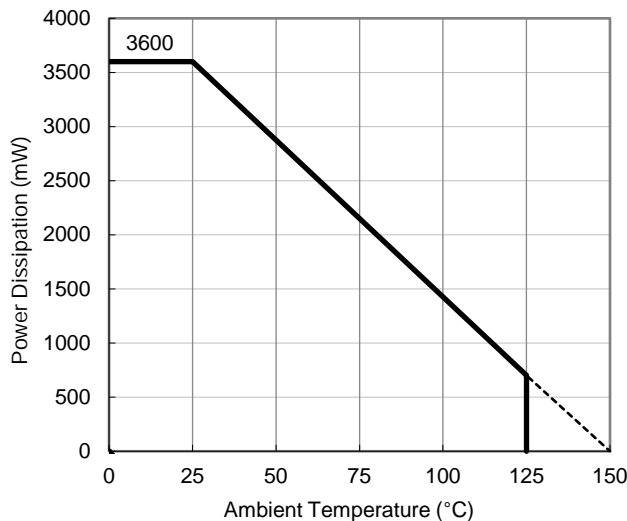
**Measurement Result**

(Ta = 25°C, Tjmax = 150°C)

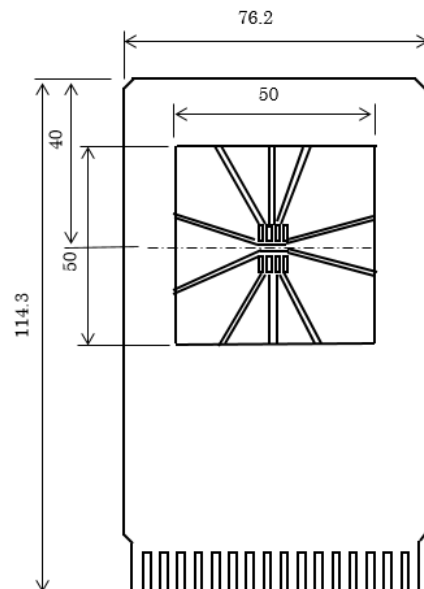
| Item   | Measurement Result                     |
|--|--|
| Power Dissipation                                  | 3600 mW                                |
| Thermal Resistance ( $\theta_{ja}$ )               | $\theta_{ja} = 34.5^{\circ}\text{C/W}$ |
| Thermal Characterization Parameter ( $\psi_{jt}$ ) | $\psi_{jt} = 10^{\circ}\text{C/W}$     |

$\theta_{ja}$ : Junction-to-Ambient Thermal Resistance

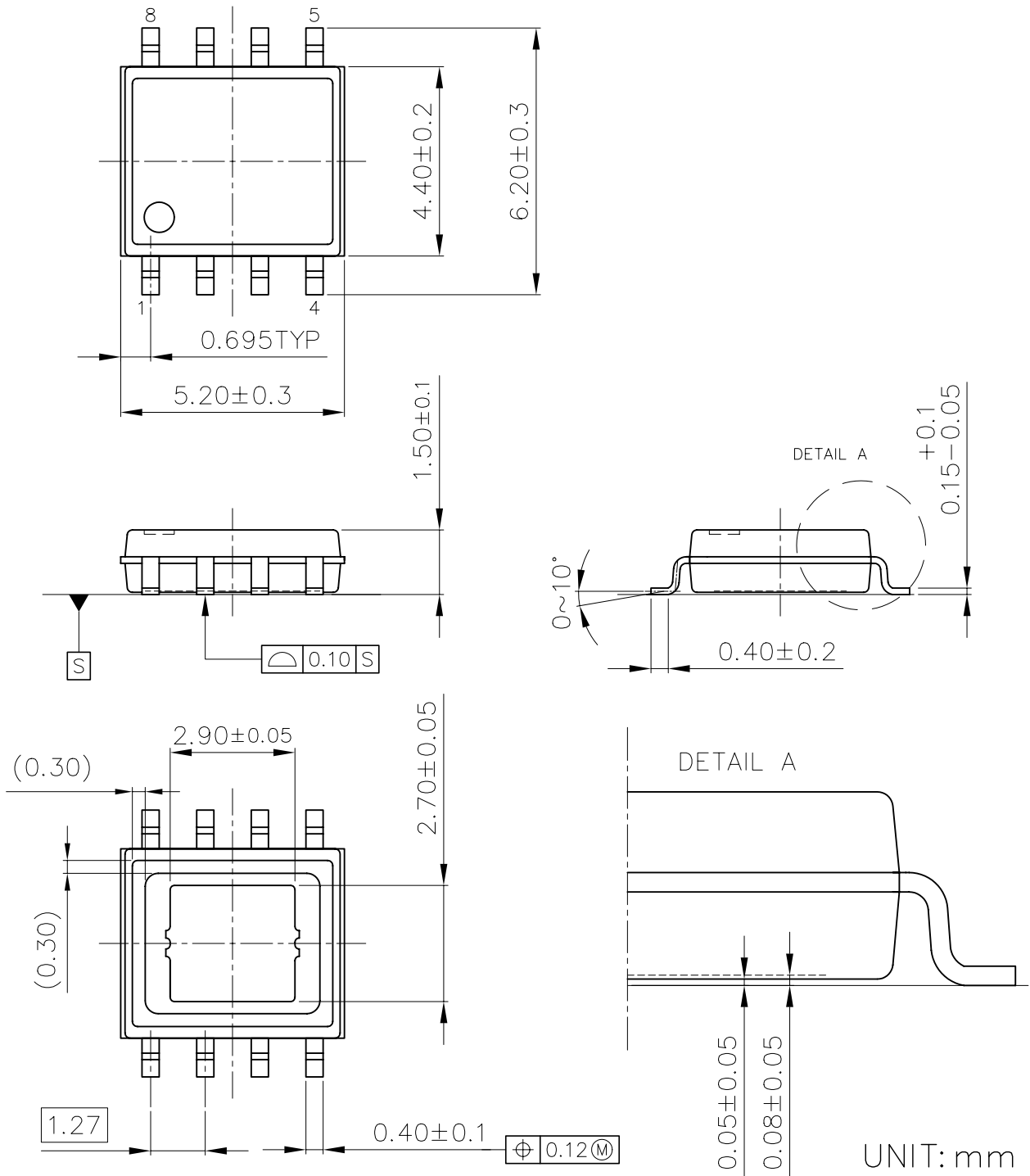
$\psi_{jt}$ : Junction-to-Top Thermal Characterization Parameter



**Power Dissipation vs. Ambient Temperature**



**Measurement Board Pattern**



UNIT: mm

HSOP-8E Package Dimensions



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